

(19) World Intellectual Property Organization
International Bureau



(43) International Publication Date
4 May 2006 (04.05.2006)

PCT

(10) International Publication Number
WO 2006/047126 A2

(51) International Patent Classification:

B32B 21/02 (2006.01) A61K 33/24 (2006.01)
B32B 21/10 (2006.01) A61K 33/34 (2006.01)

(21) International Application Number:

PCT/US2005/037303

(22) International Filing Date: 18 October 2005 (18.10.2005)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:

10/970,446 21 October 2004 (21.10.2004) US

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(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, LY, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SM, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, LV, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

— without international search report and to be republished upon receipt of that report

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: MICRONIZED WOOD PRESERVATIVE FORMULATIONS

(57) Abstract: The present invention provides wood preservative compositions comprising micronized particles. In one embodiment, the composition comprises dispersions of micronized metal or metal compounds. In another embodiment, the wood preservative composition comprises an inorganic component comprising a metal or metal compound and organic biocide. When the composition comprises an inorganic component and an organic biocide, the inorganic component or the organic biocide or both are present as micronized particles. When compositions of the present invention are used for preservation of wood, the micronized particles can be observed as uniformly distributed within the wood and there is minimal leaching of the metal and biocide from the wood.

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MICRONIZED WOOD PRESERVATIVE FORMULATIONS

FIELD OF THE INVENTION

The present invention is related generally to the field of wood preservatives and more particularly to a wood preservative composition comprising micronized particles.

BACKGROUND OF THE INVENTION

Wood preserving compositions are well known for preserving wood and other cellulose-based materials, such as paper, particleboard, textiles, rope, etc., against organisms responsible for the destruction of wood, including fungi and insects. Many conventional wood preserving compositions contain copper amine complexes. Copper amine complexes have been used in the past because the amine solubilizes the copper in aqueous solutions. The copper in such copper amine complexes is obtained from a variety of copper bearing materials, such as copper scrap, cuprous oxide, copper carbonate, copper hydroxide, a variety of cuprous and cupric salts, and copper bearing ores. The amine in such copper amine complexes is normally obtained from an aqueous solution of ammonia and ammonium salts, such as ammonium carbonate, and ammonium sulfate, ethanolamines, etc. For example, U.S. patent no. 4,622,248 describes forming copper amine complexes by dissolving copper (II) oxide [CuO] (also known as cupric oxide) in ammonia in the presence of ammonium bicarbonate.

The disadvantage of using ammonia as a copper solubilizing agent lies in the strong odor of ammonia. Additionally, copper ammonia preservatives can affect the appearance of the treated wood giving surface residues an undesirable color. In recent years, many amine-containing compounds, such as the ethanolamines and aliphatic polyamines, have been used to replace ammonia to formulate water-soluble copper solutions. These compounds were chosen because of their strong complexing ability with copper and because they are essentially odorless. U.S. patent no. 4,622,248 discloses a method of preparing copper amine complexes by dissolving a mixture of copper (II) carbonate [CuCO₃] and copper (II) hydroxide [Cu(OH)₂] in ethanolamine and water. The complexing amine (i.e., the ligand) and copper (II) ion combine stoichiometrically and thus the weight ratio of reagents will be different for each complexing amine. However, copper amine based preservatives have higher copper loss due to leaching as compared to traditional copper based preservatives such as chromated copper arsenate (CCA).

In addition to metal biocides, existing wood preservatives can also contain organic biocides. However, many organic biocides currently in use are not water soluble. Therefore, solubilizing agents, surfactants and wetting agents are often added to either solubilize or form emulsions of the organic biocide to formulate a product that is suitable for the treatment of wood or other cellulose substrates.

However, the solubilizing agents, surfactants, and wetting agents are costly and the use of these products may result in enhanced leaching of the biocides when the treated material comes into contact with moisture. Such enhanced leaching is considered to be the result of the solubilizing agents, surfactants and wetting agents which remain in the wood after treatment. Because these compounds continue to cause leaching of the metal and/or biocide from the treated wood, field performance problems or environmental issues can result.

Despite many efforts to address these deficiencies in existing wood preservatives, there has been an unmet need to produce aqueous metal-based preservatives that are suitable for treating wood and other cellulose-based materials while minimizing the undesirable leaching of metal ions and/or biocide from treated materials when exposed to water. This need is met by the invention disclosed herein.

SUMMARY OF THE INVENTION

The present invention provides micronized compositions for preservation of wood. In one embodiment, the compositions comprise metal or metal compounds as micronized particles.

In another embodiment, the compositions comprise metal or metal compounds and organic biocides. The metal is in an insoluble (micronized) form. The metal compounds may be in a soluble form or in a water insoluble (micronized) form. The organic biocides may be soluble or water insoluble (micronized). In the compositions of this embodiment, at least one component (either a metal/metal compound or a biocide) is micronized.

Accordingly, in one embodiment is provided a wood preservative composition comprising micronized metal, metal compounds or combinations thereof.

In another embodiment is provided a wood preservative composition comprising a micronized metal or metal compound and a soluble organic biocide.

In another embodiment is provided a wood preservative composition comprising micronized metal/metal compounds and micronized organic biocides.

In another embodiment is provided a composition comprising soluble metal compound and micronized organic biocides.

Also provided is a method for using the compositions of the present invention. The method comprises the step of contacting a cellulosic material, such as wood, with a composition of the present invention. When the compositions of the present invention are used for preservation of wood, there is minimal leaching of the metal or metal and the biocide from wood.

In one embodiment, the preferred metal for wood preserving type applications is copper in the form of a copper compound having a particle size 0.001 microns to 25.0 microns. The copper compound can optionally be mixed with a variety of water soluble and/or water insoluble biocides and then vacuum impregnated, vacuum/pressure or dip impregnated into cellulosic material by standard methods to effectively preserve the material from agents that degrade cellulosic material such as fungi, insects, bacteria etc.

BRIEF DESCRIPTION OF THE FIGURES

Figure 1A is a comparison of copper leaching from wood treated with copper monoethanolamine (copper mea) vs. micronized copper hydroxide at copper retentions of 0.1 pounds per cubic foot (pcf) and 0.2 pcf according to American Wood Preservers' Association (AWPA) Standard E11-97 "Standard Method of Determining the Leachability of Wood Preservatives".

Figure 1B is a comparison of copper leaching from wood treated with a commercial copper based formulation ACQ-Type D and micronized copper carbonate plus dimethyldidecylammonium carbonate/bicarbonate (quat) at preservative retentions of 0.25 pcf and 0.40pcf. The leaching test was conducted following the procedure described in AWPA Standard E11-97 "Standard Method of Determining the Leachability of Wood Preservatives".

Figure 2 depicts the anatomy of coniferous wood.

Figure 3 depicts the border pit structure for coniferous wood.

Figure 4A depicts the uniform copper penetration in wood treated with micronized copper hydroxide according to AWPA Standard A3-00 "Standard Method for Determining Penetration of Preservatives and Fire Retardants".

Figure 4B depicts the uniform copper penetration in wood treated with micronized copper carbonate plus quat. The determination of copper penetration was conducted

following the procedures described in AWWA Standard A3-00 "Standard Method for Determining Penetration of Preservatives and Fire Retardants".

Figure 5 depicts the uniform particle distribution of cupric oxide through the cells of the wood treated with micronized CuO.

5 Figure 6 depicts a scanning Electron Micrograph of a Southern Pine wood treated with a micronized copper carbonate dispersion showing two views at magnification of 1600X.

DETAILED DESCRIPTION OF THE INVENTION

Unless stated otherwise, such as in the examples, all amounts and numbers used in
10 this specification are intended to be interpreted as modified by the term "about". Likewise, all elements or compounds identified in this specification, unless stated otherwise, are intended to be non-limiting and representative of other elements or compounds generally considered by those skilled in the art as being within the same family of elements or
15 compounds. The term "micronized" as used herein means a particle size in the range of 0.001 to 25 microns. Furthermore, it should be understood that "micronized" does not refer only to particles which have been produced by the finely dividing, such as by mechanical grinding, of materials which are in bulk or other form. Micronized particles can also be formed by other mechanical, chemical or physical methods, such as, for example, formation
20 in solution, with or without a seeding agent, grinding or impinging jet. The term "preservative" as used herein means a composition that renders the material to which it is applied more resistant to insect, fungal or microbial attack than the same material without having the composition applied. The term "particle size" refers to the largest axis of the particle, and in the case of a generally spherical particle, the largest axis is the diameter.

The wood preservative compositions of the present invention comprise an inorganic
25 component comprising a metal, metal compound or combinations thereof and optionally one or more organic biocides. Accordingly, the present invention provides micronized wood preservatives comprising one or more metal or metal compounds with or without one or more organic biocides. When the composition comprises both the metal/metal compounds and the organic biocides, the metal or metal compounds or the organic biocides are present as water
30 insoluble micronized particles. In one embodiment, both the inorganic component and the organic biocide are present as micronized particles.

These compositions are used for treatment of cellulosic material such as wood. The leaching of metal from the treated wood is less for the present compositions than that observed from wood treated with non-micronized compositions.

A preferred metal is copper. Accordingly, in one embodiment, copper, copper
5 compounds and/or copper complexes are used. The copper or copper compounds such as cuprous oxide (a source of copper (I) ions), cupric oxide (a source of copper (II) ions), copper hydroxide, copper carbonate, basic copper carbonate, copper oxychloride, copper 8-hydroxyquinolate, copper dimethyldithiocarbamate, copper omadine, copper borate, copper residues (copper metal byproducts) or any suitable copper source can be used as micronized
10 particles having a particle size between 0.001 microns to 25 microns. These particles exhibit a relatively low solubility in water. Other metals, metal compounds or metal complexes as well as transition metals or transition metal compounds (including the lanthanide and actinide series elements) such as zinc, cadmium, silver, nickel, arsenic, bismuth, lead, chromium etc. can be used in place of copper, copper compounds or copper complexes.

15 The present invention includes any copper based compounds or copper complexes including chromated copper arsenates and other complexes. The present invention is not limited to ionically bound metals, and compounds in which the bonds to the metal are partially or totally covalent may be used.

The micronized particles can be obtained by wetting/dispersing and grinding copper
20 compounds using a commercially available grinding mill or any other chemical, physical or mechanical means. Alternatively, the micronized copper compounds may also be purchased from commercial sources, which generally need to be ground further to be useful for wood preservation. For example, micronized copper hydroxide can be obtained from Phibro-Tech, Inc., Sumter, South Carolina and ground further for use in the present invention. Micronized
25 cupric oxide can also be obtained from Nanophase Technologies Corporation, Romeoville, Illinois.

The copper source can be mixed with water with or without addition of a commercially available rheological additive such as a cellulosic derivative to form a finely dispersed suspension which can be mixed with a biocide to form a preservative system which
30 is suitable to treat and protect wood from agents causing degradation. Other metals or metal compounds as well as transition metals or transition metal compounds (including the lanthanide and actinide series elements) such as tin, zinc, cadmium, silver, nickel, etc. and compounds thereof can be used in place of copper and copper compounds. The resulting

metal dispersion or the metal biocide fluid dispersion are suitable for the preservation of wood and other cellulose-based materials.

The compositions of the present invention can be adjusted to the desired pH. For example, the pH can be adjusted to between 2 to 13 by the addition of acids or alkaline components. The acid or alkaline components can be added before, during or after preparation of the micronized particles.

The present invention includes the situation in which a water-soluble inorganic biocide is used in conjunction with a micronized organic biocide. A range of water-soluble inorganic biocides can be used. Included in this range are water-soluble compounds which could otherwise be used as micronized inorganic biocides in other embodiments of the present invention. Examples of such are water-soluble compounds in the list of copper compounds above. Other examples are compounds such as sodium fluoride, sodium borate, and boric acid. In general, the inorganic biocide has a solubility which is greater than 10 grams per liter.

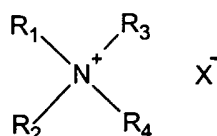
The organic biocides useful in the present invention can be water soluble as well as water insoluble. Such organic biocides including fungicides, insecticides, moldicides, bactericides, algacides etc. are well known to those skilled in the art and include azoles, quaternary ammonium compounds, borate compounds, fluoride compounds and combinations thereof.

Some non-limiting examples of water soluble biocides are quaternary ammonium compounds, such as alkyl dimethylbenzylammonium chloride, dimethyldidecylammonium chloride, dimethyldidecylammonium carbonate/bicarbonate and the like.

Water insoluble organic biocides are also well known. Some non-limiting examples of water insoluble organic biocides are provided below.

Fungicides, insecticides and bactericides that can be used with the system are well known to those skilled in the art and include azoles, quaternary ammonium compounds, boron compounds, fluoride compounds disclosed herein and combinations thereof.

Quaternary ammonium compounds that can be mixed with micronized metal formulations have the following structures:



where R1, R2, R3, and R4 are independently selected from alkyl or aryl groups and X⁻ selected from chloride, bromide, iodide, carbonate, bicarbonate, borate, carboxylate, hydroxide, sulfate, acetate, laurate, or any other anionic group. Preferred quaternary ammonium compounds include alkyldimethylbenzylammonium chloride,

5 alkyldimethylbenzylammonium carbonate/bicarbonate, dimethyldidecylammonium chloride, dimethyldidecylammonium carbonate/bicarbonate, etc.

Examples of fungicides which can be mixed with micronized metal formulations are provided in Table 1:

10

Table 1

<p>Aliphatic Nitrogen Fungicides butylamine; cymoxanil; dodicyn; dodine; guazatine; iminoctadine</p>
<p>Amide Fungicides carpropamid; chloraniformethan; cyazofamid; cyflufenamid; diclocymet; ethaboxam; fenoxanil; flumetover; furametpyr; prochloraz; quinazamid; silthiofam; triforine; benalaxyl; benalaxyl-M; furalaxyl; metalaxyl; metalaxyl-M; pefurazoate; benzohydroxamic acid; tioxymid; trichlamide; zarilamid; zoxamide; cyclafuramid; furmecyclox dichlofluanid; tolylfluanid; bentiavalicarb; iprovalicarb; benalaxyl; benalaxyl-M; boscalid; carboxin; fenhexamid; metalaxyl; metalaxyl-M; metsulfovax; ofurace; oxadixyl; oxycarboxin; pyracarbolid; thifluzamide; tiadinil; benodanil; flutolanil; mebenil; mepronil; salicylanilide; tecloftalam fenfuram; furalaxyl; furcarbamil; methfuroxam; flusulfamide</p>
<p>Antibiotic Fungicides aureofungin; blasticidin-S; cycloheximide; griseofulvin; kasugamycin; natamycin; polyoxins; polyoxorim; streptomycin; validamycin; azoxystrobin; dimoxystrobin; fluoxastrobin; kresoxim-methyl; metominostrobin; oryastrobin; picoxystrobin; pyraclostrobin; trifloxystrobin</p>
<p>Aromatic Fungicides biphenyl; chlorodinitronaphthalene; chloroneb; chlorothalonil; cresol; dicloran; hexachlorobenzene; pentachlorophenol; quintozone; sodium pentachlorophenoxide; tecnazene</p>
<p>Benzimidazole Fungicides</p>

benomyl; carbendazim; chlorfenazole; cypendazole; debacarb; fuberidazole; mecarbinzid; rabenzazole; thiabendazole
Benzimidazole Precursor Fungicides furophanate; thiophanate; thiophanate-methyl
Benzothiazole Fungicides bentaluron; chlobenthiazone; TCMTB
Bridged Diphenyl Fungicides bithionol; dichlorophen; diphenylamine
Carbamate Fungicides benthiavalicarb; furophanate; iprovalicarb; propamocarb; thiophanate; thiophanate-methyl; benomyl; carbendazim; cypendazole; debacarb; mecarbinzid; diethofencarb, iodopropynyl butylcarbamate
Conazole Fungicides climbazole; clotrimazole; imazalil; oxpoconazole; prochloraz; triflumizole; azaconazole; bromuconazole; cyproconazole; diclobutrazol; difenoconazole; diniconazole; diniconazole-M; epoxiconazole; etaconazole; fenbuconazole; fluquinconazole; flusilazole; flutriafol; furconazole; furconazole-cis hexaconazole; imibenconazole; ipconazole; metconazole; myclobutanil; penconazole; propiconazole; prothioconazole; quinconazole; simeconazole; tebuconazole; tetraconazole; triadimefon; triadimenol; triticonazole; uniconazole; uniconazole-P
Dicarboximide Fungicides famoxadone; fluoroimide; chlozolate; dichlozoline; iprodione; isovaledione; myclozolin; procymidone; vinclozolin; captafol; captan; ditalimfos; folpet; thiochlorfenphim
Dinitrophenol Fungicides binapacryl; dinobuton; dinocap; dinocap-4; dinocap-6; dinoceton; dinopenton; dinosulfon; dinoterbon; DNOC
Dithiocarbamate Fungicides azithiram; carbamorph; cufraneb; cuprobam; disulfiram; ferbam; metam; nabam; tecoram; thiram; ziram; dazomet; etem; milneb; mancopper; mancozeb; maneb; metiram; polycarbamate; propineb; zineb
Imidazole Fungicides cyazofamid; fenamidone; fenapanil; glyodin; iprodione; isovaledione; pefurazoate; triazoxide

Morpholine Fungicides aldimorph; benzamorf; carbamorph; dimethomorph; dodemorph; fenpropimorph; flumorph; tridemorph
Organophosphorus Fungicides ampropylfos; ditalimfos; edifenphos; fosetyl; hexylthiofos; iprobenfos; phosdiphen; pyrazophos; tolclofos-methyl; triamiphos
Oxathiin Fungicides carboxin; oxycarboxin
Oxazole Fungicides chlozolate; dichlozoline; drazoxolon; famoxadone; hymexazol; metazoxolon; myclozolin; oxadixyl; vinclozolin
Pyridine Fungicides boscalid; buthiobate; dipyrithione; fluazinam; pyridinitril; pyrifenox; pyroxychlor; pyroxyfur
Pyrimidine Fungicides bupirimate; cyprodinil; diflumetorim; dimethirimol; ethirimol; fenarimol; ferimzone; mepanipyrim; nuarimol; pyrimethanil; triarimol
Pyrrole Fungicides fempiclonil; fludioxonil; fluoroimide
Quinoline Fungicides ethoxyquin; halacrinat; 8-hydroxyquinoline sulfate; quinacetol; quinoxifen
Quinone Fungicides benquinox; chloranil; dichlone; dithianon
Quinoxaline Fungicides chinomethionat; chlorquinox; thioquinox
Thiazole Fungicides ethaboxam; etridiazole; metsulfovax; octhilineone; thiabendazole; thiadifluor; thifluzamide
Thiocarbamate Fungicides methasulfocarb; prothiocarb
Thiophene Fungicides ethaboxam; silthiofam
Triazine Fungicides anilazine

<p>Triazole Fungicides bitertanol; fluotrimazole; triazbutil</p>
<p>Urea Fungicides bentaluron; pencycuron; quinazamid</p>
<p>Other Fungicides acibenzolar acypetacs allyl alcohol benzalkonium chloride benzamacril bethoxazin carvone chloropicrin DBCP dehydroacetic acid diclomezine diethyl pyrocarbonate fenaminosulf fenitropan fenpropidin formaldehyde furfural hexachlorobutadiene iodomethane isoprothiolane methyl bromide methyl isothiocyanate metrafenone nitrostyrene nitrothal-isopropyl OCH 2 phenylphenol phthalide piperalin probenazole proquinazid pyroquilon sodium orthophenylphenoxide spiroxamine sultropen thicyofen tricyclazole; chitin; chitosan; 4-cumylphenol, , 4-alpha-cumylphenol.</p>

Examples of insecticides which can be mixed micronized metal formulations are shown in Table 2:

Table 2

<p>Antibiotic Insecticides allosamidin; thuringiensin; spinosad; abamectin; doramectin; emamectin eprinomectin; ivermectin; selamectin; milbemectin; milbemycin oxime; moxidectin</p>
<p>Botanical Insecticides anabasine; azadirachtin; <i>d</i>-limonene; nicotine; pyrethrins cinerins; cinerin I; cinerin II; jasmolin I; jasmolin II; pyrethrin I; pyrethrin II; quassia; rotenone; ryania sabadilla</p>
<p>Carbamate Insecticides bendiocarb; carbaryl; benfuracarb; carbofuran; carbosulfan; decarbofuran; furathiocarb; dimetan; dimetilan; hyquincarb; pirimicarb; alanycarb; aldicarb; aldoxycarb; butocarboxim; butoxycarboxim; methomyl; nitrilacarb; oxamyl; tazimcarb; thiocarboxime; thiodicarb; thiofanox; allyxycarb aminocarb; bufencarb; butacarb; carbanolate; cloethocarb; dicresyl; dioxacarb; EMPC; ethiofencarb; fenethacarb; fenobucarb; isoprocarb; methiocarb; metolcarb; mexacarbate; promacyl; promecarb; propoxur; trimethacarb; XMC; xylylcarb</p>
<p>Dinitrophenol Insecticides dinex; dinoprop; dinosam; DNOC; cryolite; sodium hexafluorosilicate; sulfluramid</p>
<p>Formamidine Insecticides</p>

amitraz; chlordimeform; formetanate; formparanate

Fumigant Insecticides

acrylonitrile; carbon disulfide; carbon tetrachloride; chloroform; chloropicrin; para-dichlorobenzene; 1,2-dichloropropane; ethyl formate; ethylene dibromide; ethylene dichloride; ethylene oxide; hydrogen cyanide; iodomethane; methyl bromide; methylchloroform; methylene chloride; naphthalene; phosphine; sulfuryl fluoride; tetrachloroethane

Insect Growth Regulators

bistrifluron; buprofezin; chlorfluazuron; cyromazine; diflubenzuron; flucycloxuron; flufenoxuron; hexaflumuron; lufenuron; novaluron; noviflumuron; penfluron; teflubenzuron; triflumuron; epofenonane; fenoxycarb; hydroprene; kinoprene; methoprene; pyriproxyfen; triprene; juvenile hormone I; juvenile hormone II; juvenile hormone III; chromafenozide; halofenozide; methoxyfenozide; tebufenozide; α -ecdysone; ecdysterone; diofenolan; precocene I; precocene II; precocene III; dicyclanil

Nereistoxin Analogue Insecticides

bensultap; cartap; thiocyclam; thiosultap; flonicamid; clothianidin; dinotefuran; imidacloprid; thiamethoxam; nitenpyram nithiazine; acetamiprid; imidacloprid; nitenpyram; thiacloprid

Organochlorine Insecticides

bromo-DDT; camphechlor; DDT; pp'-DDT; ethyl-DDD; HCH; gamma-HCH; lindane; methoxychlor; pentachlorophenol; TDE; aldrin; bromocyclen; chlorbicyclen; chlordane; chlordecone; dieldrin; dilor; endosulfan; endrin; HEOD; heptachlor; HHDN; isobenzan; isodrin; kelevan; mirex

Organophosphorus Insecticides

bromfenvinfos; chlorfenvinphos; crotoxyphos; dichlorvos; dicrotophos; dimethylvinphos; fospirate; heptenophos; methocrotophos; mevinphos; monocrotophos; naled; naftalofos; phosphamidon; propaphos; schradan; TEPP; tetrachlorvinphos; dioxabenzofos; fosmethilan; phenthoate; acethion; amiton; cadusafos; chlorethoxyfos; chlormephos; demephion; demephion-O; demephion-S; demeton; demeton-O; demeton-S; demeton-methyl; demeton-O-methyl; demeton-S-methyl; demeton-S-methylsulphon; disulfoton; ethion; ethoprophos; IPSP; isothioate; malathion; methacrifos; oxydemeton-methyl; oxydeprofos; oxydisulfoton; phorate; sulfotep; terbufos; thiometon; amidithion; cyanthoate; dimethoate; ethoate-methyl; formothion; mecarbam; omethoate; prothoate; sophamide; vamidothion chlorphoxim;

phoxim; phoxim-methyl; azamethiphos; coumaphos; coumithoate; dioxathion; endothon; menazon; morphothion; phosalone; pyraclofos; pyridaphenthion; quinothion; dithicrofos; thicrofos; azinphos-ethyl; azinphos-methyl; dialifos; phosmet; isoxathion; zolaprofos; chlorprazophos; pyrazophos; chlorpyrifos; chlorpyrifos-methyl; butathiofos; diazinon; etrimfos; lirimfos; pirimiphos-ethyl; pirimiphos-methyl; primidophos; pyrimitate; tebupirimfos; quinalphos; quinalphos-methyl; athidathion; lythidathion; methidathion; prothidathion; isazofos; triazophos; azothoate; bromophos; bromophos-ethyl; carbophenothion; chlorthiophos; cyanophos; cythioate; dicapthon; dichlofenthion; etaphos; famphur; fenchlorphos; fenitrothion; fensulfothion; fenthion; fenthion-ethyl; heterophos; jodfenphos; mesulfenfos; parathion; parathion-methyl; phenkapton; phosnichlor; profenofos; prothiofos; sulprofos; temephos; trichlormetaphos-3; trifenofos; butonate; trichlorfon; mecarphon; fonofos; trichloronat; cyanofenphos; EPN; leptophos; crufomate; fenamiphos; fosthietan; mephosfolan; phosfolan; pirimetaphos; acephate; isocarbophos; isofenphos; methamidophos; propetamphos; dimefox; mazidox; mipafox

Oxadiazine Insecticides

indoxacarb

Phthalimide Insecticides

dialifos; phosmet; tetramethrin

Pyrazole Insecticides

acetoprole; ethiprole; fipronil; tebufenpyrad; tolfenpyrad; vaniliprole

Pyrethroid Insecticides

acrinathrin; allethrin; bioallethrin; barthrin; bifenthrin; bioethanomethrin; cyclethrin; cycloprothrin; cyfluthrin; beta-cyfluthrin; cyhalothrin; gamma-cyhalothrin; lambda-cyhalothrin; cypermethrin; alpha-cypermethrin; beta-cypermethrin; theta-cypermethrin; zeta-cypermethrin; cyphenothrin; deltamethrin; dimefluthrin; dimethrin; empenthrin; fenfluthrin; fenpirithrin; fenpropathrin; fenvalerate; esfenvalerate; flucythrinate; fluvalinate; tau-fluvalinate; furethrin; imiprothrin; metofluthrin; permethrin; biopermethrin; transpermethrin; phenothrin; prallethrin; profluthrin; pyresmethrin; resmethrin; bioresmethrin; cismethrin; tefluthrin; terallethrin; tetramethrin; tralomethrin; transfluthrin; etofenprox; flufenprox; halfenprox; protrifenbute; silafluofen

Pyrimidinamine Insecticides

flufenerim; pyrimidifen

Pyrrole Insecticides chlorfenapyr
Tetronic Acid Insecticides spiromesifen
Thiourea Insecticides diafenthuron
Urea Insecticides flucofuron; sulcofuron
Other Insecticides closantel; clorpyrifos, crotamiton; EXD; fenazaflor; fenoxacrim; hydramethylnon; isoprothiolane; malonoben; metoxadiazone; nifluridide; pyridaben; pyridalyl; rafoxanide; triarathene; triazamate

Examples of bactericides are shown in Table 3:

Table 3

Bactericides bronopol; 2-(thiocyanatomethylthio) benzothiazole (busan), cresol; dichlorophen; dipyrithione; dodicin; fenaminosulf; formaldehyde; hydrargaphen; 8-hydroxyquinoline sulfate; kasugamycin; nitrapyrin; octhiline; oxolinic acid; oxytetracycline; probenazole; streptomycin; tecloftalam thiomersal. Isothiazolone-type bactericides such as, for example, Kathon 930, Kathon WT, Methylisothiazolinone, Benzisothiazolin-3-one and 2-octyl-3- isothiazolone.

5 Some preferred organic biocides are listed in Table 4 below:

Table 4

Organic Biocides Useful for Wood Protection

Name	Formula and CAS#
Azoles:	
Cyproconazole	C ₁₅ H ₁₈ ClN ₃ O: 94361-06-5
Propiconazole	C ₁₅ H ₁₇ Cl ₂ N ₃ O ₂ : 60207-90-1
Tebuconazole	C ₁₆ H ₂₂ ClN ₃ O: 107534-96-3

Busan (TCMTB) 2-(thiocyanatomethylthio) benzothiazole	C ₉ H ₆ N ₂ S ₃ : 21564-17-0
Chlorothalonil	C ₈ Cl ₄ N ₂ : 1897-45-6
Dichlofluanid	C ₉ H ₁₁ Cl ₂ FN ₂ O ₂ S ₂ : 1085-98-9
Isothiazolone: Kathon 930 Kathon WT Methylisothiazolinone Benzisothiazolin-3-one 2-octyl-3-isothiazolone	C ₁₁ H ₁₇ Cl ₂ NOS: 64359-81-5 C ₄ H ₄ CINOS: 26172-55-4 C ₄ H ₅ NOS: 2682-20-4 C ₇ H ₅ NOS: 2634-33-5 C ₁₁ H ₁₉ NOS: 26530-20-1
Imidacloprid	C ₉ H ₁₀ CIN ₅ O ₂ : 138261-41-3
Iodopropynyl Butylcarbamate (IPBC)	C ₈ H ₁₂ INO ₂ : 55406-53-6
Pyrethroids: Bifenthrin Cypermethrin Permethrin	C ₂₃ H ₂₂ ClF ₃ O ₂ : 82657-04-3 C ₂₂ H ₁₉ Cl ₂ NO ₃ : 52315-07-8 C ₂₁ H ₂₀ Cl ₂ O ₃ : 52645-53-1
Chitin	1398-61-4
Chitosan	9012-76-4
Clorpyrifos	C ₉ H ₁₁ Cl ₃ NO ₃ PS: 2921-88-2
4-cumylphenol	C ₁₅ H ₁₆ O: 599-64-4
Fipronil	C ₁₂ H ₄ Cl ₂ F ₆ N ₄ OS: 120068-37-3
Carbendazim	C ₉ H ₉ N ₃ O ₂ : 10605-21-7
Cyfluthrin	C ₂₂ H ₁₈ Cl ₂ FNO ₃ : 68359-37-5
4-alpha-Cumylphenol	C ₁₅ H ₁₆ O: 599-64-4

Other biocides known by those skilled in the art that can optionally be used with the system would include insecticides, mold inhibitors, algacides, bactericides and the like which may also be added to this system to further enhance the performance of this disclosure.

5 The insoluble biocides can be micronized into particles of submicron size ranging from 0.001 micrometers to 25 micrometers using a grinding mill. The particles are dispersed in standard dispersants such as acrylic copolymers, aqueous solution of copolymers with

where n is an integer which can vary from 1 to 4, R₁, R₂ and R₃ are independently selected from the group consisting of hydrogen, methyl, ethyl and phenyl, and a, b and c are each integers which can be 1 to 6, and R₄ is fatty alkyl of C₈ to C₂₂.

5 Wood treated with the micronized preservatives of the present invention exhibits reduced leaching. Accordingly, if wood is treated with micronized copper, copper compounds, copper complexes or combinations thereof such that copper or copper ions are present at a concentration of greater than 0.001 pcf, the leaching of copper from the wood is less than 50% of leaching observed with non-micronized formulations. In another
10 embodiment, at concentrations of copper or copper ions in treated wood greater than 0.001 pcf, the leaching of copper is less than 20% of leaching observed with non-micronized formulations. In yet another embodiment, at concentrations of copper or copper ions in treated wood between 0.001 and 0.05 pcf, the leaching of copper is less than 20% of leaching observed from wood containing greater than 0.001 pcf of non-micronized copper. Preferably,
15 the leaching of copper is less than 10%, and more preferably less than 5%, of leaching observed with non-micronized copper formulations when the concentration of copper or copper ions is between 0.001 to 0.5 pcf.

When wood is treated with micronized wood preservatives formulations disclosed herein, metal leaching is reduced. For example, as shown in Figure 1A, when wood is treated
20 with Cu-MEA composition the leaching of copper is about 12% and 24% respectively for 0.1 pcf (pounds per cubic feet) copper and 0.2 pcf copper. In contrast when the wood is treated with a micronized composition of the present invention the leaching was only about 2% and 1% respectively for the 0.1 pcf copper and 0.2 pcf copper. Copper leaching was evaluated following the procedures described in American Wood Preservers' Association Standard
25 E11-97.

Similarly, Figure 1B is a comparison of copper leaching from wood treated with a commercial copper based formulation ACQ-Type D and micronized copper carbonate plus dimethyldidecylammonium carbonate/bicarbonate (quat) at preservative retentions of 0.25 pcf and 0.40pcf. The leaching test was conducted following the procedure described in
30 AWWPA Standard E11-97 "Standard Method of Determining the Leachability of Wood Preservatives". It can be seen that wood treated with micronized copper carbonate based formulation demonstrated much greater copper leaching resistance than the wood treated with the commercially available preservative Ammoniacal Copper Quat (ACQ)-Type D.

Also important is the penetration of the dispersion formulation into the wood's or other cellulose-based material's cellular structure. If the copper source used in formulating the dispersion formulation disclosed herein has a particle size in excess of 30 microns, the particles may be filtered by the surface of the wood and thus may not be uniformly distributed within the cell and cell wall. As shown in Figure 2, the primary entry and movement of fluids through wood tissue occurs primarily through the tracheids and border pits. Tracheids have a diameter of about thirty microns. Fluids are transferred between wood cells by means of border pits.

The overall diameter of the border pit chambers typically varies from a several microns up to thirty microns while, the diameter of the pit openings (via the microfibrils) typically varies from several hundredths of a micron to several microns. Figure 3 depicts the border pit structure for coniferous woods.

When wood is treated with micronized preservative formulation, if the particle size of the micronized preservative is less than the diameter of the pit openings, a complete penetration and a uniform distribution of micronized preservative in wood is expected. Figure 4A depicts the complete copper penetration in wood treated with micronized copper hydroxide according to AWWA Standard A3-00 "Standard Method for Determining Penetration of Preservatives and Fire Retardants". A uniform blue was observed indicating the presence of copper. Figure 4B depicts the complete copper penetration in wood treated with micronized copper carbonate plus quat. Again, a uniform blue color was observed indicating the presence of copper. The determination of copper penetration was conducted following the procedures described in AWWA Standard A3-00 "Standard Method for Determining Penetration of Preservatives and Fire Retardants". Figure 5 depicts the uniform particle distribution of cupric oxide through the cells of the wood treated with micronized CuO through the observation of Scanning Electron Microscope (SEM). The particles were confirmed to be copper compounds by the use of SEM-Energy Dispersed X-ray Analysis (EDXA).

Particle size of the metal, metal compounds or organic biocide used in the dispersion formulation disclosed herein typically does not exceed 30 microns or the metal and or organic biocide used in conjunction with the metal tends to be filtered by the surface of the wood thus not attaining a desired penetration and fluid flow through the wood tissue. In one embodiment particle size of the micronized particles used in the dispersion formulation disclosed herein can be between 0.001-10 microns. In another embodiment, the particle size

is between 0.005 to 1.0 micron. In another embodiment, the particle size is between 0.05 to 10.0 microns. If a more uniform penetration is desired, particle size of the metal/metal compounds or the organic biocide used in the dispersion formulation disclosed herein can be between 0.05-1.0 microns.

5 The present invention also provides a method for preservation of wood. In one embodiment, the method comprises the steps of treating wood with a composition (treating fluid) comprising a dispersion of water insoluble micronized metal and/or metal compounds. In another embodiment, wood is treated with a composition comprising a dispersion of micronized metal and/or metal compounds and organic biocides, wherein the organic
10 biocides are soluble or present as water insoluble micronized particles. The size of the micronized particles for the metal/metal compounds and organic biocide is between 0.001 to 25 microns, preferably between 0.005 to 10 microns, more preferably between 0.05 to 10 micron and even more preferably between 0.05 to 1.0 microns. In another embodiment, the wood is treated with a composition comprising soluble metal compounds and micronized
15 organic biocides.

 The present invention is not limited to applications which involve micronized particles which have been applied to wood as such. For example, the wood preservative effect of micronized particles can be realized by the formation of such particles in situ. By in situ, it is meant that particle formation takes place on or within the wood. Thus, the benefits
20 of the present invention can be realized if particle formation takes place, for example, within the tracheids of the wood to be preserved. Additionally or instead, particle formation can take place outside of the tracheids, with the subsequent movement of at least some of the particles into the tracheids. Such a movement can be caused by, for example, pressure cycling, such as described in the examples. The micronized particles generally have an
25 average size which is small enough to enable at least partial penetration of wood by particle migration through tracheids and border pits.

 Thus, the present invention also provides a method for the preparation of wood containing the micronized particle preservative biocidal compositions of the present invention. The method comprises forming micronized particles of metal compound, biocide,
30 or both, on or within the wood to be protected.

 The treating fluid may be applied to wood by dipping, soaking, spraying, brushing, or any other means well known in the art. In a preferred embodiment, vacuum and/or pressure techniques are used to impregnate the wood in accord with this invention including the

standard processes, such as the "Empty Cell" process, the "Modified Full Cell" process and the "Full Cell" process, and any other vacuum and /or pressure processes which are well known to those skilled in the art.

The standard processes are defined as described in AWWA Standard C1-03 "All
5 Timber Products – Preservative Treatment by Pressure Processes". In the "Empty Cell"
process, prior to the introduction of preservative, materials are subjected to atmospheric air
pressure (Lowry) or to higher air pressures (Rueping) of the necessary intensity and duration.
In the "Modified Full Cell", prior to introduction of preservative, materials are subjected to a
vacuum of less than 77kPa (22 inch Hg) (sea level equivalent). A final vacuum of not less
10 than 77 kPa (22 inch Hg) (sea level equivalent) shall be used. In the "Full Cell Process",
prior to introduction of preservative or during any period of condition prior to treatment,
materials are subjected to a vacuum of not less than 77kPa (22 inch Hg). A final vacuum of
not less than 77 kPa (22 inch Hg) is used.

It should be understood that unless specifically set forth in conjunction with a method,
15 the term "treatment" as used herein should not be construed as pertaining only to the
application of micronized particles to wood which is to be preserved, but also includes in situ
formation of micronized formation.. Thus, the term "treatment," should generally be
construed to encompass all methods as a result of which micronized particles are present in
the wood. Thus, the term "treated wood" is only intended to mean wood comprising
20 micronized particles, irrespective of the mode of formation/delivery of the micronized
particles.

Furthermore, wood which contains a preservative composition of the present
invention generally has the advantage of being less corrosive of nails and other metal
implements than wood which contains other commonly used preservative compositions
25 which contain amine compounds. Nails which contain iron, copper, nickel, (and other metals
which would be used in nails and would have some susceptibility to alkaline corrosion)
and/or other metals which are susceptible to alkaline corrosion will generally show some
degree of corrosion after exposure to wood which contains non-micronized amine-containing
preservative formulations. The same type nails when exposed to wood containing a
30 micronized metal preservative can generally be expected to show less or no corrosion after an
equivalent exposure period.

Moreover, in comparison to wood which has been treated with commonly available
preservatives, wood which has been treated with micronized preservatives of the present

invention is particularly resistant to mold growth. Without desiring to be bound by theory, it is thought that the amines and other nitrogenous compounds in currently used preservative compositions serve as an energy source for molds. Because the disclosed preservative compositions containing micronized copper are free of amines, wood which has been treated
5 with them can be found to have less mold than wood which has been treated with other compositions and similarly exposed.

Wood which comprises micronized biocidal formulations generally exhibits reduced biocide leaching relative to wood which contains non-micronized biocidal compositions. Without desiring to be bound by theory, it is thought that the ability of a given component to
10 be solvated in an aqueous environment is one of the most important considerations with respect to leaching. All other variables being equal, easily solvated compounds and ions exhibit greater leaching than chemical species which may not have the same ability to be solvated in a given aqueous environment. Thus, the presence of a biocide in micronized form prevents much of the biocide from being in direct contact with the aqueous environment,
15 reducing its ability to be solvated. In environments which are conducive to leaching, the result is reduced leaching.

Wood treated with the compositions of the present invention has been observed to have a uniform distribution of micronized particles. This can be observed simply in the coloration (when a colored composition is used) or it can also be observed via the use of
20 microscopy. For example, when scanning electron microscopy is combined with energy dispersive X-ray analysis (SEM-EDXA), the presence of, as well as the distribution of the micronized particles can be observed. SEM-EDXA is also useful for determination of the elements present in the micronized particles and therefore, the composition of the particles can be determined. Alternatively or additionally, specific staining methods can be carried out
25 on SEM sections to determine the identity of the composition of the particles.

The following examples are provided to further describe certain embodiments of the invention but are in no way meant to limit the scope of the invention. Examples 1 through 5 demonstrate the formulation of the concentrated dispersions of copper compounds and the concentrated dispersions of copper compounds comprising various organic biocides.
30 Examples 6 through 14 demonstrate the preparation of treating fluids using concentrated dispersions for the treatment of wood.

Example 1

500g of copper hydroxide were added to a container containing 1091.7 grams of water and 75.0 grams of commercially available dispersants/wetting agents. The mixture was mechanically stirred for 5 minutes and then placed in a grinding mill. The sample was
5 ground for about 30 minutes, and a stable dispersion containing about 30% copper hydroxide was obtained. The particle size of the copper hydroxide dispersion was analyzed by Horiba LA-910 Particle Size Distribution Analyzer (PSDA). The average particle size was 0.195 micrometers (um) with a distribution range of 0.04 um to 1.5 um.

Example 2

1000 grams of basic copper carbonate was mixed with 2158.3 grams of water and 175.0 grams of commercially available wetting agents/dispersants. The mixture was mechanically stirred for 10 minutes. The mixture was then placed in a grinding mill and ground for about 20 minutes. A stable dispersion was obtained with an average particle size
15 of 0.199 micrometers.

Example 3

1000 grams of basic copper carbonate and 20 grams of tebuconazole were mixed with 3780 grams of water and 200 grams of wetting agents/dispersants. The mixture was
20 mechanically stirred for about 10 minutes. The mixture was then placed in a grinding mill and ground for about 30 minutes. A stable dispersion containing 25% basic copper carbonate and 0.5% tebuconazole was obtained with an average particle size of 0.200 micrometers.

Example 4

300 grams of copper 8-hydroxyquinolate (Cu-8) were mixed with 855 grams of water and 45 grams of dispersants. The mixture was mechanically mixed for about 5 minutes and placed in a grinding mill. The mixture was ground for about 30 minutes and a stable dispersion containing 25% Cu-8 was obtained with an average particle size of 0.282
30 micrometers.

Example 5

A stable cupric oxide (CuO) dispersion containing about 30% CuO was supplied by Nanophase Technologies, Inc. The average particle size was about 0.1 micrometers. This can be mixed with organic soluble or micronized biocides.

5

Example 6

38.5g of cupric hydroxide dispersion from Example 1 was mixed with 7.5g of N, N-dimethyl-1-dodecylamine-N-oxide (AO) and 2954.0g of water to produce a preservative treating fluid containing 0.385% cupric hydroxide and 0.25% AO. The fluid was then used to treat 2" x 4" x 10" samples of southern pine sapwood, and sealed with epoxy resin, using an initial vacuum of 28" Hg for 15 minutes, followed by a pressure cycle of 135 psi for 25 minutes and a final vacuum of 27" Hg for 10 minutes. The resulting treated wood was weighed and found to have doubled its weight. The treated sample was cut and the cross sections sprayed with a copper indicator to determine copper penetration following the procedure described in American Wood Preservers' Association Standard A3-00, and the blue color indicates the presence of copper. The sample was found to have 100% uniform distribution of copper throughout the cross section as in Figure 4A. As a comparison, Figure 4A also showed the cross section of untreated wood.

10

15

Example 7

50.0g CuO dispersion from Example 5 were mixed with 2942.5g of water and 7.5g of didecylmethylammonium chloride. The product was mixed until uniformly dispersed and the treating solution containing the following compositions was obtained:

20

Components	Percent
Cupric Oxide	0.50
Didecylmethylammonium Chloride	0.25

25

A southern pine stake measuring 1.5" x 3.5" x 10" was placed in a laboratory retort with a vacuum of 27" Hg for 15 minutes. The treating solution was then pumped into the retort and the retort pressurized to 130 psi for 30 minutes. The solution was drained from the retort and the test stake weighed. Based on the weight pickup, the test stake doubled its weight and showed uniform penetration of the cupric oxide throughout the wood cross section. A sample taken from the center portion of the treated wood was submitted for

scanning electron microscopy (SEM) analysis, and the SEM result indicated the uniform particle distribution in wood as shown in Figure 5.

Example 8

5 4000g of treating fluid containing 0.31% of cupric oxide and 0.16%
didecyldimethylammonium carbonate were prepared by mixing CuO dispersion from
Example 5 and didecyldimethylammonium carbonate. The fluid was used to treat 2" x 4" x
10" southern pine samples by placing the samples in a chamber and drawing a 27" Hg
vacuum for 10 minutes. The treating fluid was then drawn into the chamber and allowed to
10 stay in contact with the wood cubes for 15 minutes. The fluid was pumped from the chamber
and the resulting wood had more than doubled its weight. Cross sections of the cubes
showed 100% copper penetration.

Example 9

15 A preservative treating formulation was prepared by adding 0.15kg of copper
carbonate dispersion from Example 2 to 0.025 kg of a quaternary ammonium compound,
dimethyl didecyl ammonium carbonate/bicarbonate and 4.825 kg of water. This fluid was
allowed to mix until a homogenous fluid was prepared. This fluid was used to treat southern
pine test stakes measuring 0.156 x 1.5 x 10.0 inches (4 x 38 x 254 mm) by the full-cell
20 process. The resulting stakes showed a uniform distribution of copper throughout the wood
cells. The treated test stakes were installed in the field to evaluate the field performance of
the preservative following the procedure described in AWPA Standard E7-01 "Standard
Method of Evaluating Wood Preservatives by Field Tests with Stakes". The test results
indicated that the treated stakes were resistant to decay and insect attack. The fluid was also
25 used to treat southern pine wood cube blocks measuring $\frac{3}{4}$ " x $\frac{3}{4}$ " x $\frac{3}{4}$ " (19mm x 19mm x
19mm). The treated cubes were exposed to several test fungi to evaluate the bio-efficacy of
the preservative formulation following the procedure described in AWPA Standard E10-01
"Standard Method of Testing Wood Preservatives by Laboratory Soil-Block Cultures". Upon
the completion of the soil-block test, the cubes were found to have less than 2.0% weight
30 loss, indicating essentially no fungal attack to the treated cubes. In comparison, untreated
wood cubes had approximately 50% weight loss after being exposed to the test fungi. The
soil block test results indicated wood treated the above preservative formulation was resistant
to fungal attack.

Example 10

A preservative treating composition was prepared by adding 0.1 kg of dispersion from Example 3 to 4.9 kg of water. The resulting fluid contained 0.50% copper carbonate and 0.01% tebuconazole. This fluid was then used to treat full-size lumber using the full-cell process wherein the wood is initially placed under a vacuum of 30" Hg for 30 minutes, followed by the addition of the treating solution. The system was then pressurized for 30 minutes at 110 psi. A final vacuum of 28" Hg for 30 minutes was applied to the wood to remove residual liquid. The wood was found to contain a uniform distribution of copper throughout the cross sections and is resistant to fungal and insect attack.

Example 11

54g of dispersion from Example 3 and 7.5g of N, N-dimethyl-1-hexadecylamine-N-oxide (AO) were mixed with 2938.5 grams of water to obtain a preservative treating fluid containing 0.45% carbonate, 0.009% tebuconazole and 0.25% AO. The resulting fluid was used to treat red pine lumber using a modified full-cell process. The resulting stakes were air-dried and found to a uniform distribution of copper throughout the cross sections and were resistant to fungal and insect attack.

Example 12

A preservative treating fluid was prepared by adding 16.0 g of Cu 8-hydroxyquinolate (Cu-8) dispersion from Example 4 to 3984.0 g of water. The resulting fluid contained 0.1% Cu-8. The fluid was used to treat southern pine lumber using a full cell process. The treated stakes were oven dried and found to contain a uniform distribution of particles throughout the cross sections and were resistant to fungal and insect attack.

Example 13

A preservative treating fluid was prepared by mixing 175g concentrated dispersion containing 20% copper carbonate and 0.5% cyproconazole with 3325.0g water. The resulting solution contained 1.0% copper carbonate and 0.025% cyproconazole and was used to treat southern pine lumber using a full cell process. The treated stakes were oven dried and found to contain a uniform distribution of copper and cyproconazole throughout the cross sections and were resistant to fungal and insect attack.

Example 14

A preservative treating fluid can be prepared by mixing copper sulfate solution and micronized cyproconazole at a concentration of 0.25% Cu and 0.01% cyproconazole. The resulting fluid can be used to treat lumber using a full cell process. The treated sample can be
5 air-dried for two weeks and tested for resistance to fungal and termite attack.

Example 15

Southern Pine wood was treated with a micronized copper carbonate dispersion from Example 9. Scanning electron microscopy with EDXA was performed by standard methods.
10 Results are shown in Figure 6. A uniform distribution of the micronized particles is observed. This examples indicates that the presence of micronized particles can be identified in treated wood and that the distribution of these particles was found to be uniform.

Although specific embodiments have been described herein, those skilled in the art will recognize that routine modifications can be made without departing from the spirit of the
15 invention.

We claim:

1. Wood comprising a wood preservative composition, wherein said composition comprises:
 - 5 (a) an inorganic component selected from the group consisting of a metal, metal compound and combinations thereof; and/or
 - (b) one or more organic biocides,wherein the inorganic component, the organic component or both are present as micronized particles and wherein a scanning electron microscopy image of a section of the
10 wood identifies the existence of said micronized particles.
2. Wood of claim 1, wherein the inorganic component is selected from the group consisting of copper, cobalt, cadmium, nickel, tin, silver, zinc, lead bismuth, chromium and arsenic and compounds thereof.
3. Wood of claim 2, wherein the micronized inorganic component is copper,
15 copper compound, copper complex or combinations thereof.
4. Wood of claim 3, wherein the copper compounds are selected from the group consisting of copper hydroxide, cupric oxide, cuprous oxide, copper carbonate, basic copper carbonate, copper oxychloride, copper 8-hydroxyquinolate, copper dimethyldithiocarbamate, copper omadine and copper borate.
- 20 5. Wood of claim 1, wherein the micronized particles have a size of between 0.001 microns to 25 microns.
6. Wood of claim 5, wherein the micronized particles have a size of between 0.001 to 10.0 microns.
7. Wood of claim 6, wherein the micronized particles have a size of between
25 0.05 to 10.0 microns.
8. Wood of claim 7, wherein the size of the micronized particles is between 0.05 to 1.0 microns.

9. Wood of claim 1, wherein the organic biocide is selected from the group consisting of biocides listed in Tables 1 through 4.

10. Wood as in claim 1, wherein the wood is further resistant to decay and insect attack as determined by American Wood Preservers' Association (AWPA) Standard E7-01 or
5 AWPA Standard E10-01.

11. Wood in which copper, copper compounds, or combinations thereof are present in amounts such that the concentration of copper or copper ions is more than 0.001 pcf and leaching of copper from said wood is less than 50% of the leaching of copper from wood containing more than 0.001 pcf of non-micronized copper, wherein leaching is
10 measured according to modified American Wood Preservers' Association Standard E11-97.

12. Wood as in claim 11, wherein copper, copper compounds, copper complexes or combinations thereof are present in amounts such that the concentration of copper or copper ions is more than 0.001 pcf and leaching of copper from said wood is less than 20% of the leaching of copper from wood containing more than 0.001 pcf of non-micronized copper,
15 wherein leaching is measured according to modified American Wood Preservers' Association Standard E11-97.

13. Wood as in claim 12, wherein said copper or copper compounds are present in amounts such that the concentration of copper or copper ions is between 0.001 pcf and 0.5 pcf and leaching of copper from said wood is less than 20% of the leaching of copper from wood containing more than 0.001 pcf of non-micronized copper, wherein leaching is
20 measured according to modified American Wood Preservers' Association Standard E11-97.

14. Wood as in claim 13, wherein said copper or copper compounds are present in amounts such that the concentration of copper or copper ions is between 0.001 pcf and 0.5 pcf and leaching of copper from said wood is less than 10% of the leaching of copper from wood containing more than 0.001 pcf of non-micronized copper, wherein leaching is
25 measured according to modified American Wood Preservers' Association Standard E11-97.

15. Wood as in claim 14, wherein said copper or copper compounds are present in amounts such that the concentration of copper or copper ions is between 0.001 pcf and 0.5 pcf and leaching of copper from said wood is less than 5% of the leaching of copper from

wood containing more than 0.001 pcf of non-micronized copper, wherein leaching is measured according to modified American Wood Preservers' Association Standard E11-97.

16. Wood as in claim 15, wherein said copper or copper compounds are present in amounts such that the concentration of copper or copper ions is between 0.001 pcf and 0.5
5 pcf and leaching of copper from said wood is less than 2% of the leaching of copper from wood containing more than 0.001 pcf of non-micronized copper, wherein leaching is measured according to modified American Wood Preservers' Association Standard E11-97.

17. Wood as in claim 11, wherein the wood is further resistant to decay and insect
10 attack as determined by American Wood Preservers' Association (AWPA) Standard E7-01 or AWPA Standard E10-01.

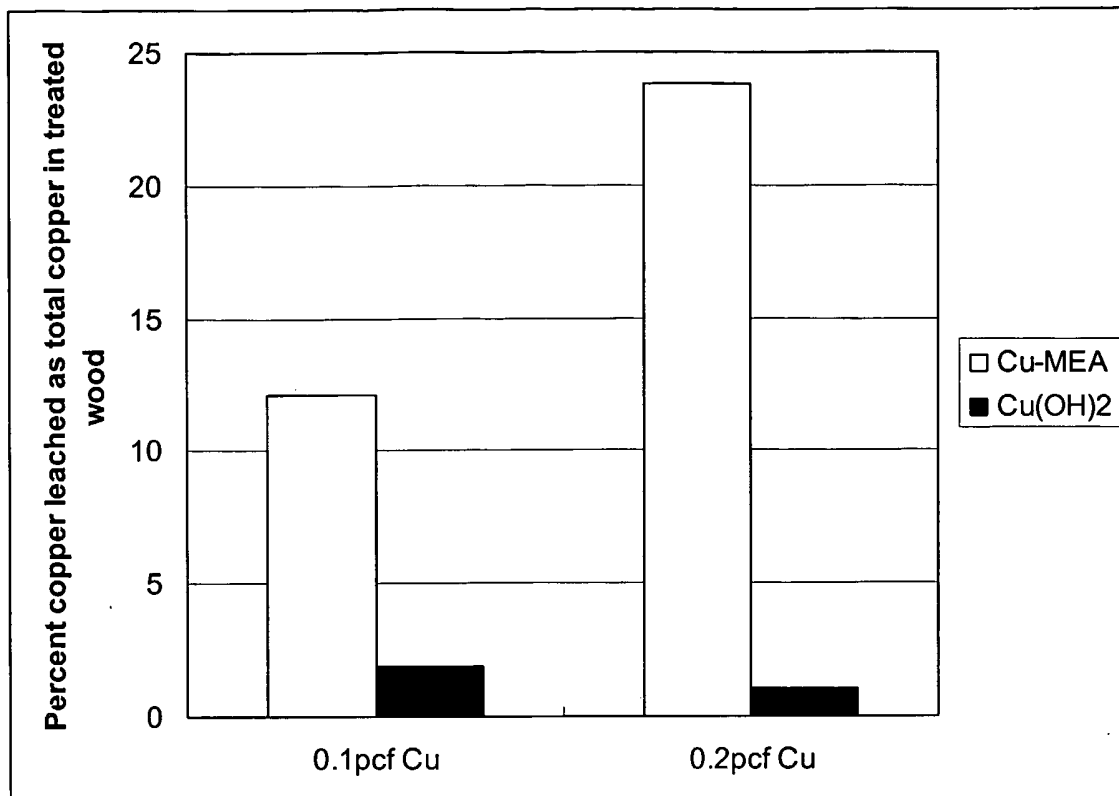


Figure 1A

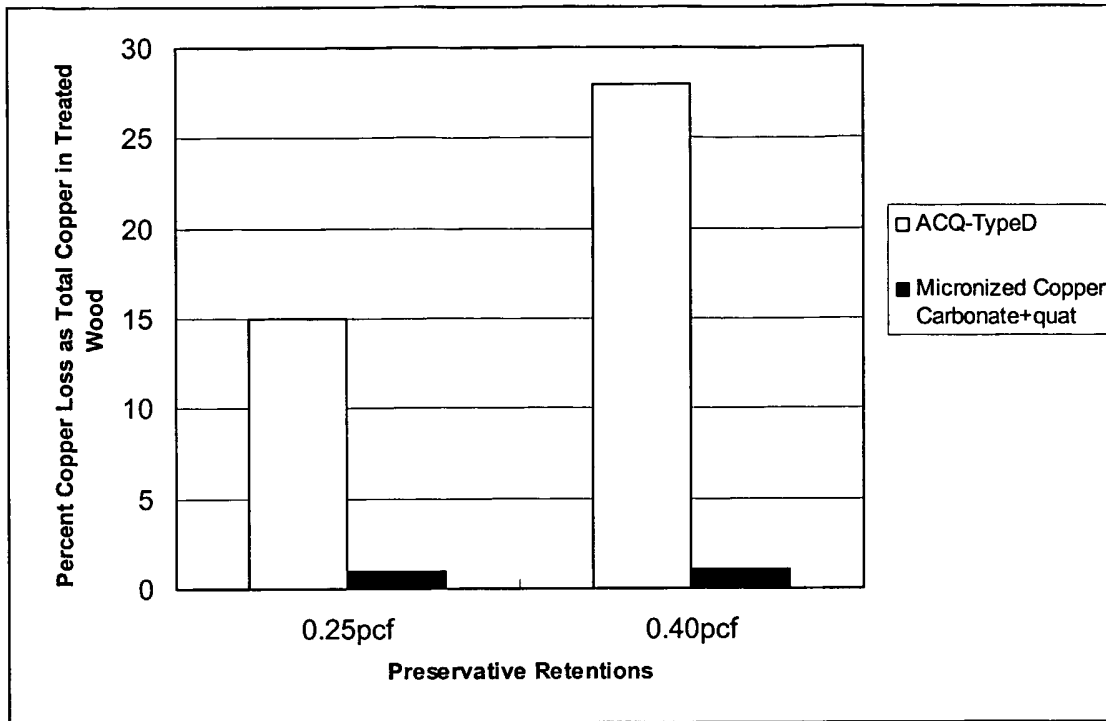
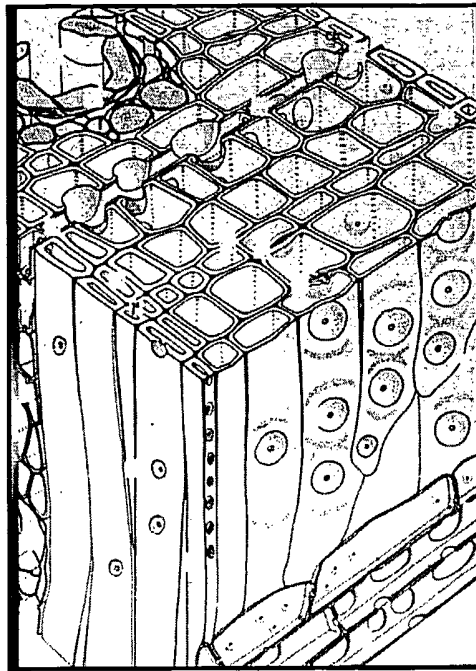
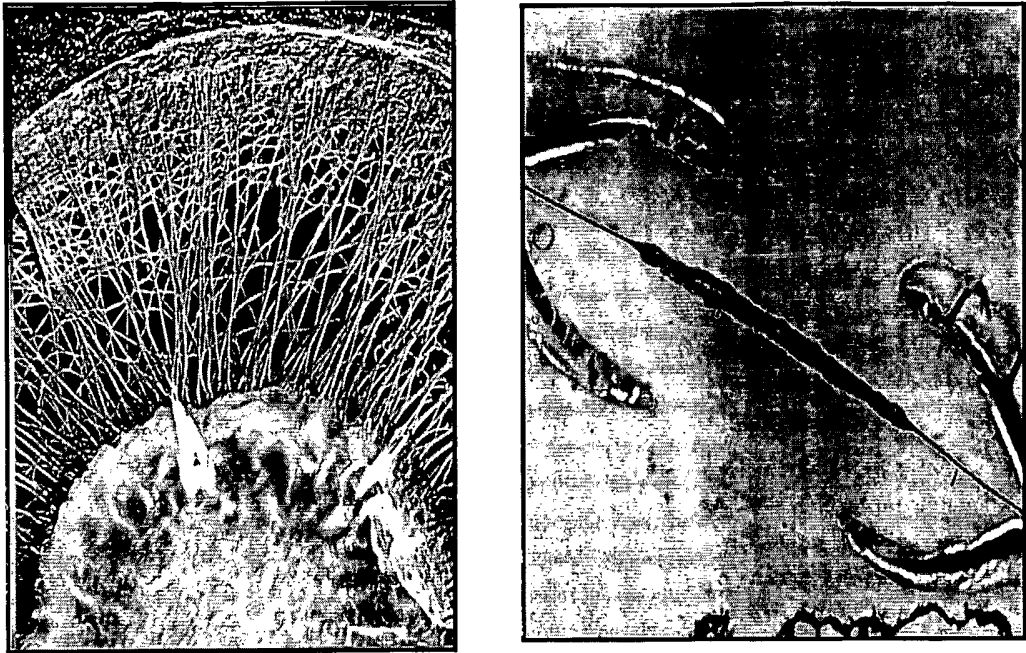


Figure 1B



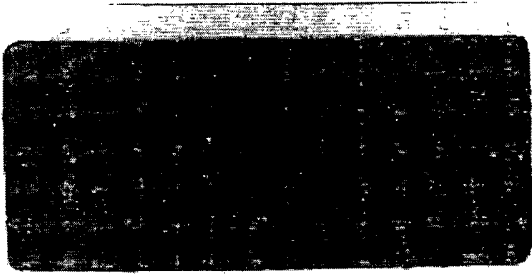
Coniferous Wood Anatomy

Figure 2

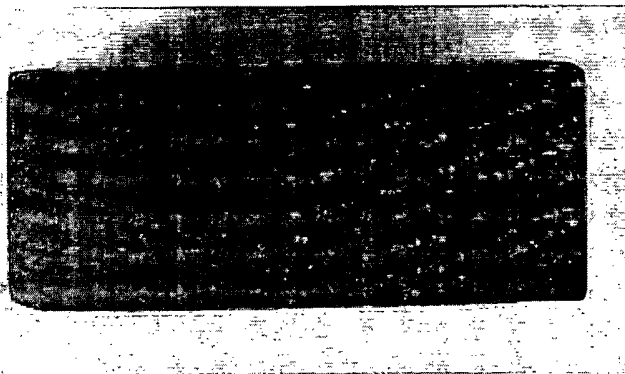


Bordered Pit

Figure 3



Cross section of micronized copper hydroxide treated wood sprayed with copper indicator



Cross section of untreated wood sprayed with copper indicator

Figure 4A

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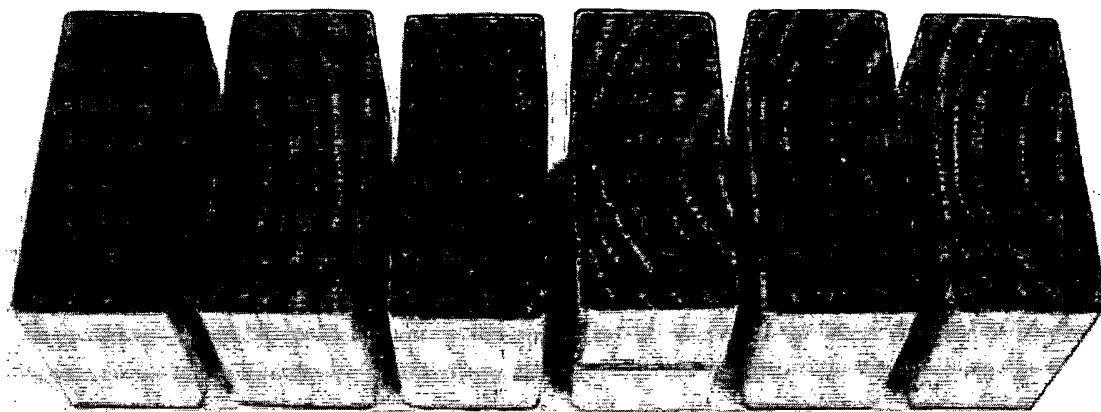


Figure 4B



Figure 5

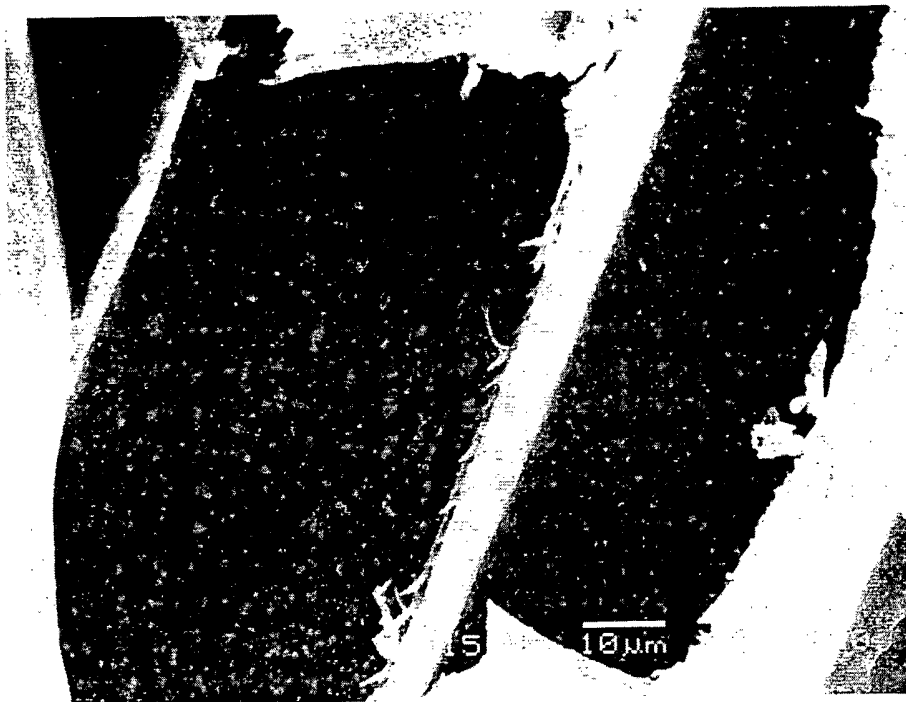


Figure 6